

## PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Tsung-Kuan Allen Chou</td> <td>08/16/2012</td> </tr> <tr> <td>Nickolai Belov</td> <td>03/18/2009</td> </tr> <tr> <td>John Heck</td> <td>08/14/2012</td> </tr> </tbody> </table>		Name	Execution Date	Tsung-Kuan Allen Chou	08/16/2012	Nickolai Belov	03/18/2009	John Heck	08/14/2012		
Name	Execution Date										
Tsung-Kuan Allen Chou	08/16/2012										
Nickolai Belov	03/18/2009										
John Heck	08/14/2012										
RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Intel Corporation</td> </tr> <tr> <td>Street Address:</td> <td>2200 Mission College Boulevard</td> </tr> <tr> <td>City:</td> <td>Santa Clara</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95052</td> </tr> </table>		Name:	Intel Corporation	Street Address:	2200 Mission College Boulevard	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95052
Name:	Intel Corporation										
Street Address:	2200 Mission College Boulevard										
City:	Santa Clara										
State/Country:	CALIFORNIA										
Postal Code:	95052										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12242843</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12242843						
Property Type	Number										
Application Number:	12242843										
CORRESPONDENCE DATA											
<p>Fax Number: 5034396073</p> <p>Phone: (503) 439-8778</p> <p>Email: christi_rouly@bstz.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: James M. Howard</p> <p>Address Line 1: 1279 Oakmead Parkway</p> <p>Address Line 4: Sunnyvale, CALIFORNIA 94085-4040</p>											
ATTORNEY DOCKET NUMBER:	42P27408										
NAME OF SUBMITTER:	James M. Howard										
<p>Total Attachments: 4</p> <p>source=P27408 Assignment signed by Chou#page1.tif</p> <p>source=P27408 Assignment signed by Chou#page2.tif</p> <p>source=P27408 Assignment signed by John Heck#page1.tif</p> <p>source=P27408 Assignment signed by John Heck#page2.tif</p>											

CH \$40.00 12242843

## **ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**TSUNG-KUAN ALLEN CHOU; NICKOLAI BELOV; JOHN HECK**

hereby sell, assign, and transfer to:

**Intel Corporation**

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

### **METHOD OF SSP CANTILEVER TO MOVER WAFER BOND STOP PROCESS**

(I hereby authorize and request my attorney, associated with Customer Number 59796, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on September 30, 2008 as

United States Application Number 12/242,843 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

~~John Heck~~

  
Tsung-Kuan Allen Chou

08/16/2012  
(Today's Date)

  
Nickolai Belov

03/18/2009  
(Today's Date)

\_\_\_\_\_  
John Heck

\_\_\_\_\_  
(Today's Date)

## **ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**TSUNG-KUAN ALLEN CHOU; NICKOLAI BELOV; JOHN HECK**

hereby sell, assign, and transfer to:

**Intel Corporation**

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

### **METHOD OF SSP CANTILEVER TO MOVER WAFER BOND STOP PROCESS**

(I hereby authorize and request my attorney, associated with Customer Number 59796, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on September 30, 2008 as

United States Application Number 12/242,843 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below.

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

~~John Heck~~

Tsung-Kuan Allen Chou

(Today's Date)



Nickolai Belov

03/18/2009

(Today's Date)



John Heck

8/14/12

(Today's Date)